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# 免責聲明



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- Information as to those factors that could cause actual results to vary can be found in iST's Annual Report and such other documents as iST may file with, or submit to, the Taipei Exchange from time on time.
- Except as required by law, we undertake no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.

# Agenda



- 一、宜特簡介
  - iST: Company Profile
- 二、財務報告

**Financial Results** 

三、未來營運概況與展望

**Future Operations Overview and Prospects** 

四、問與答

Q&A



# 公司簡介

電子產業醫學中心

創立時間Founded:1994年

掛牌時間Listing date:2004年

資本額Capitalization:約7.43億元

(NTD 743Million)

員工人數Employee Number:1200+人

董事長 /總經理 Chairman /CEO:

余維斌 Danny Yu 🥮

認識宜特 iST Introduction: (集)





## 宜特里程碑

### iST Milestones



#### Milestones

#### 1994

 Founded the company in Hsinchu, Taiwan, the company changed the existing verification model of the entire semiconductor industry with its initial service- IC FIB.



#### 2000

 Established the Reliability Assurance (RA) Lab.

#### 2002

 Established an operating location in Shanghai, China, to actively develop the China market.

#### 2005

 Established an operating location in Kunshan, China, to continue expanding the market in China.



#### 1999

 Established the Failure Analysis (FA) Lab.

#### 2001

 Acquired the laboratory accreditation for the IECQ ISO/IEC 17025 quality system.

#### 2004

 Became a public company listed on the Taipei Exchange with the stock code 3289.

#### 2006

- Acquired the TÜV NORD and ISO 9001 Quality Management System certificates.
- Joining IPC International, Inc. (The Global Association for Electronics Manufacturing) and participated in establishing and developing industry standards.

#### 2018

- Established Hsinchu Plant II to enter the back-end process area of wafers.
- Acquired the TÜV NORD ISO 9001: 2015 management system certificate.



#### 2015

 Established the "DEKRA IST" as a joint venture with DEKRA, a European company, extend our global verification business to the European market.





#### 2011

 Selected by the Republic of China Fine Manufacturer Association as the First Brand, recognizing that iST's premium service quality is the best choice for customers.

#### 2007

- Established operating locations in the USA, as well as Beijing and Shenzhen China. Acquired the CNAS certificate to align with the global leading trends.
- Became a member of SMTA, providing professional and premium SMT technology.

#### 2017

 Founded headquarters in Hsinchu Science Park to provide customers with promptest and most complete solutions.



#### 2014

國家太空中

- Established the Signal Integrity (SI) Lab.
- Acquired the official authorization from Simplay Labs as a lab under the HDMI/ MHL testing system.

#### 2010

 Established the Material Analysis (MA) Lab.



#### 2019

- Won the "5th Taiwan Mittelstand Award" from the Economy Ministry, being recognized for high competitive strength on global markets with outstanding operating performance.
- Won the Moving Award from the Chinese Lean Management Association (CLMA) for our continuous improvement of competitive strength.
- Acquired the TÜV NORD ISO 14001: 2015 environmental management system certificate.
- Acquired the TÜV NORD ISO 45001: 2018 occupational health and safety management system certificate.

#### 2020

- Collaborated with the Taiwan Space Agency (TASA) and industryacademia-research institutions to form the "Taiwan Space Radiation Environment Verification and Testing Alliance (TSREVTA) to enter the international space market.
- Acquired the IEC-61340-5-1:2016 certificate for protection against electrostatic discharge.
- Acquired the ISO/IEC 27001; 2013 information security management system certificate.

#### 2021

- Acquired the 7th National Industrial Innovation Award from the Economy Ministry, recognized by the government for our contributions to domestice industries.
- Won the global top 10 semiconductor packaging solution provider award from the Semiconductor Review in the U.S.A.
- Acquired the ANSI/ESD S20.20:2021 certificate for protection against electrostatic discharge.

#### 2022

- Acquired the membership of the Automotive Electronics Council (AEC) and became a navigator for IC design and semiconductor companies entering the automotive electronics field.
- Established a laboratory in Zhubei.
- Recognized as the "Outstanding E-Invoice Business Entity" by the Ministry of Finance.

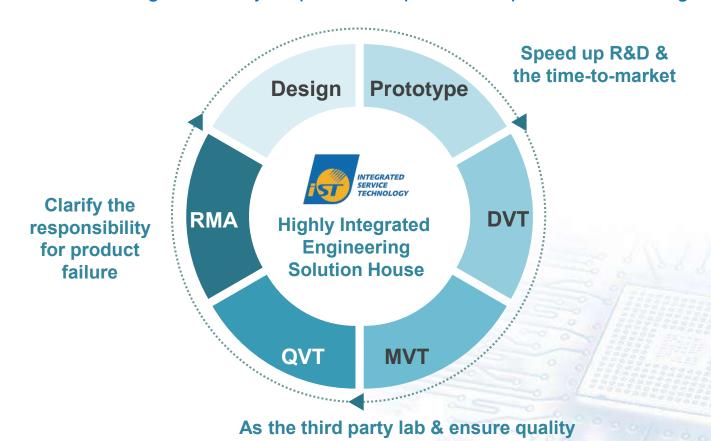


### 宜特定位 iST Position



- Provide solutions that exceed customer expectations, accelerating time-to-market.
- Serve as a third-party impartial laboratory, assisting clients in ensuring product quality.

From cradle to grave, every step of the IC process requires iST's oversight.



### 宜特的價值: 為客戶創造更大價值



iST Value: Creating Greater Value for Our Customers

**加速研發•驅動創新** 

Accelerating R&D, Driving Innovation



\_ 嚴控品質 • 精準把關

**Ensuring Quality, Delivering Precision** 



**2** 解決痛點•委案無憂

Solving Challenges, Easing Engagements

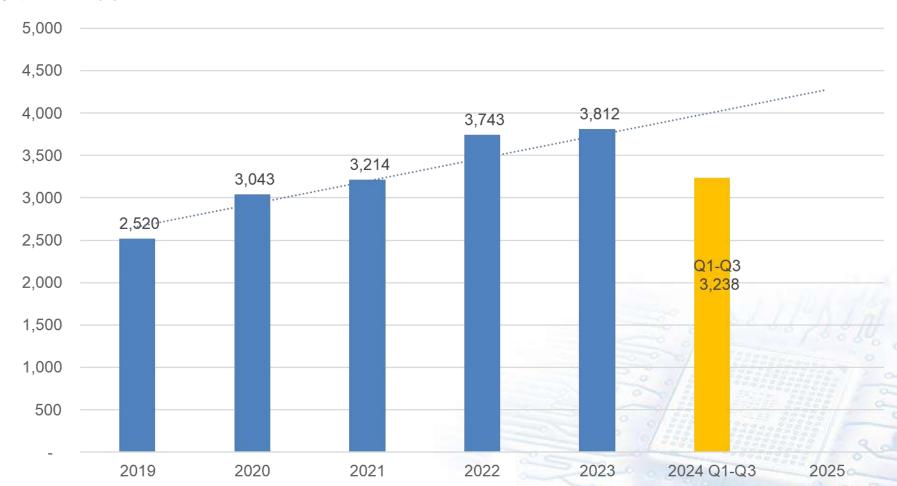




### 宜特近年營收 iST Revenue in Recent Years



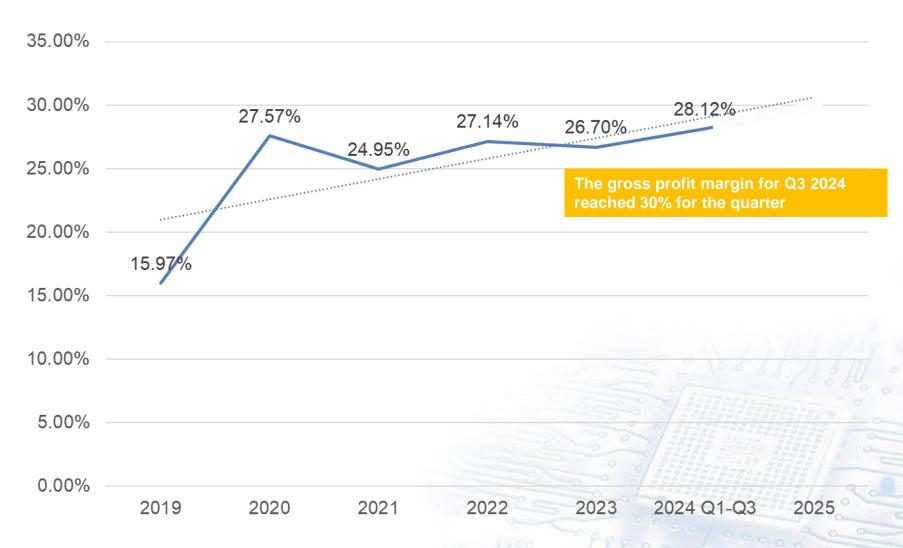
#### **Unit: NTD in millions**



## 宜特近年毛利率



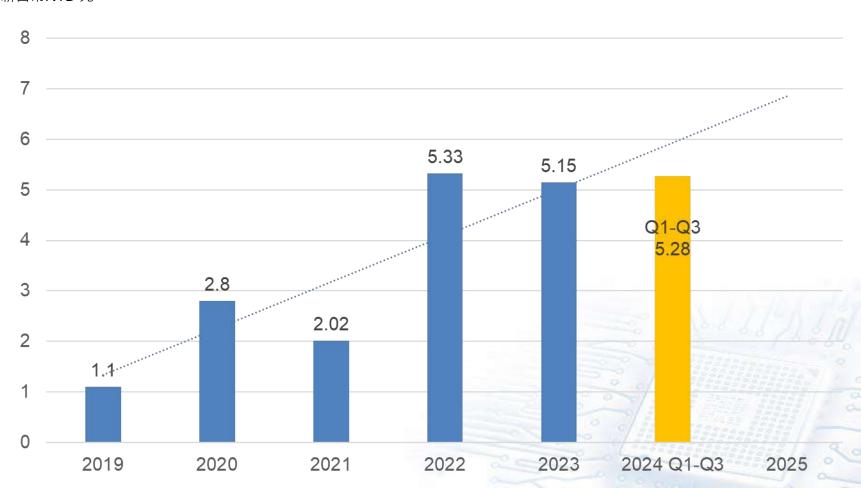
### iST Gross Profit Margin (%) in Recent Years



# **宣特近年EPS**iST EPS in Recent Years



#### 單位:新台幣NTD元



# 宜特2024年Q3綜合損益表摘要



iST 2024 Q3 Summary of Income Statement

#### 單位:新台幣百萬元

綜合損益表項目	2024Q3		2024Q2		QoQ		2023Q3		YoY	
	金額	%	金額	%	金額	G%	金額	%	金額	G%
營業收入Operating revenue	1,116	100	1,053	100	63	6	933	100	183	20
營業成本Operating Costs	781	70	760	72	21	3	709	76	72	10
營業毛利Gross profit from operations	335	30	293	28	42	14	224	24	111	50
營業費用Operating expenses	216	19	214	20	2	1	177	19	39	22
營業淨利Net operating income	119	11	79	8	40	51	47	5	72	153
營業外收(支) Total non-operating income and expenses	-8	-1	118	11	-126	-107	11	1	-19	-173
本期淨利(歸屬於母公司) Profit (loss) attributable to:Owners of parent	85	8	172	16	-87	-51	92	10	-7	-8
基本每股盈餘(新台幣元) EPS(NT Dollar)	1.15		2.33		-1.18	-51	1.22		-0.07	-6
			44//3-			10/0				13

# 宜特2024年Q3資產負債表摘要



單位:新台幣百萬元

iST 2024 Q3 Summary of Balance Sheet

資產負債表重要科目	2024.09.30		2024.06.30		QoQ		2023.09.30		YoY	
	金額	%	金額	%	金額	G%	金額	%	金額	G%
現金及約當現金Cash and cash equivalents	798	10	753	10	45	6	850	11	-52	-6
應收票據、應收帳款及應收帳款- 關係人Notes and accounts receivable,net	1,641	20	1,625	21	16	1	1,646	21	-5	_
採用權益法之投資Investments accounted for using equity method	727	9	729	9	-2	1	820	11	-93	-11
不動產、廠房及設備Property, plant and equipment	3,987	50	3,951	50	36	1	3,902	50	85	2
資產總計Total Assets	8,028	100	7,908	100	120	2	7,819	100	209	3
短期借款Short-term borrowings	819	10	733	9	86	12	901	11	-82	-9
長期借款Long-term borrowings	1,920	24	1,822	23	98	5	1,758	23	162	9
負債總計Total Liabilities	4,549	57	4,390	56	159	4	4,291	55	258	6
權益總計Total Equity	3,479	43	3,518	44	-39	-1	3,528	45	-49	-1

註:資產負債表中個別資產及負債科目金額未達總資產

之9%不予表達

# 宜特2024年Q3財務指標



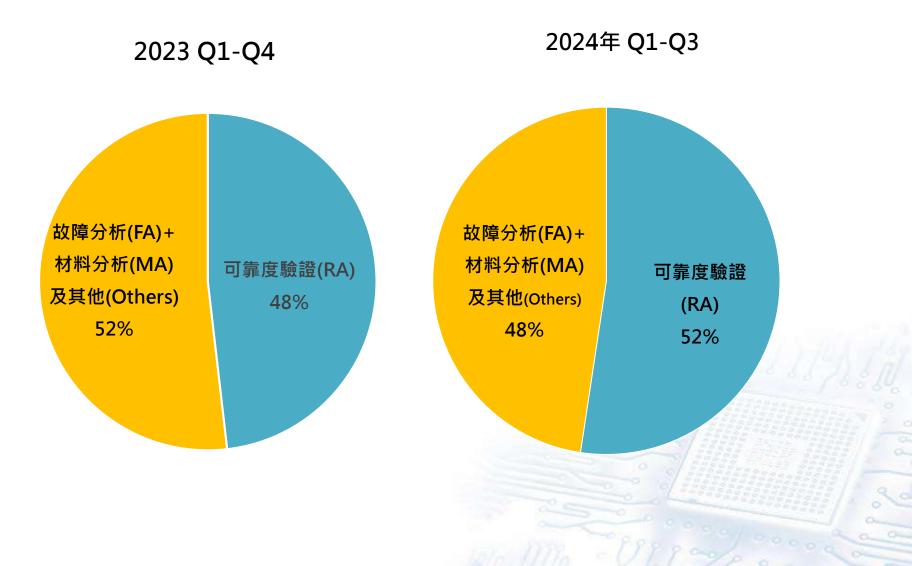
iST 2024 Q3 Financial Benchmark

	2024.9.30	2024.06.30	QoQ	2023.9.30	YoY
應收帳款週轉天數 Days Sales Outstanding(DSO)	134	135	(1)	142	(8)
應付帳款週轉天數 Days Payable Outstanding(DPO)	26	26	0	33	(7)
流動比率 Current Ratio	113%	112%	1%	119%	-6%

# 宜特2024年Q3營收比重



iST 2024 Q3 Revenue Breakdown





### 宜特1.0服務項目

iST 1.0 Service Items



#### 功能性測試

找出樣品功能喪失/故障真因

故障分析

Failure Analysis

#### 品質保證

測試樣品可維持的壽命時間/ 是否過終端客戶要求

可靠度驗證

Reliability Assurance

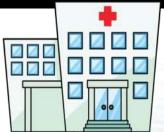


材料分析

Material Analysis

新技術製程開發

微觀尺寸的材料成分、特性與結構



訊號測試

Signal Integrity

相容性測試

不同裝置產品訊號是否互通

### 宜特2.0 iST 2.0 Total Solution



四大服務項目

故障分析 Failure Analysis

可靠度驗證 Reliability **A**ssurance

材料分析 Material Analysis

訊號測試 Signal Integrity

### 五大解決方案

# 太空環境測試

**Space Environment Testing** 

# A 高速驗證

Al High-Speed Verification

# 汽車電子驗證

**Automotive Electrical Reliability** 

# 智慧即時全球

可靠度

**Smart Global Reliability** 

### 先進製程/先進封裝

Advanced Process /Advanced Package

### 太空環境測試







### AI高速驗證







### 汽車電子驗證



**Automotive Electrical Reliability** 



## 智慧即時全球可靠度驗證中心



### iST Smart Global Reliability Center

- 市場現況 Market Status
- Industry standards lag, requiring tailored tests for EVs and AI.
- New technologies like CPO need custom modules due to no standards.

### 測試需求 Testing Requirements

 Flexible testing adapts to diverse demands and early anomaly detection ensures prototype reliability.

### 核心優勢 Core Advantage

 Equipped with hardware-software integration capabilities to deliver customized solutions, combining resources and module development to meet diverse market needs.

**Smart monitoring** 

real-time response

**Global Connection** 

### 重點市場 Target Customer

- Markets: Al, electric vehicles, high-power/high-voltage products, CPO.
- Customers: Foundries, ASICs, non-standard logic products.

# 先進製程 / 先進封裝



### Advanced Process / Advanced Package

**CPO Testing** 

Market Trend: Two key alliances, the HiSilicon Photonic Alliance (HiSPA) and SEMI Silicon Photonics Industry Alliance, have recently been established.

iST offers silicon photonics material analysis and CPO photodetector (PD) reliability verification to ensure diode quality and performance, enhancing applications in HPC, AI, LiDAR, and biomedical sensing.

**TGV Testing** 

TGV Technology widely used in RF, optical, and MEMS high-frequency applications, especially for 5G communications and high-power devices. iST provides comprehensive TGV process verification, including non-destructive and cross-sectional verification, ensuring process quality and structural integrity.

TSV Verification for BPD

Backside Power Delivery (BPD), a technology enabling power delivery from the chip's backside, freeing IC's front space, reducing interference, and boosting performance. iST conducts nano-scale to ensure etching precision, improving yield and reliability.

2.5D / 3D Advanced Packaging Testing

In 2.5D/3D advanced packaging, iST provides accelerated reliability testing (e.g., temperature-humidity, thermal cycling) and single-die failure analysis for vertically stacked HBM, ensuring product quality.

### 子公司宜錦科技





### **ProPowertek 2.0 is Launching!**

New platform to help develop new customers and strengthen cooperation with existing ones, leveraging turnkey effects!

### **Company Positioning**

Energy-efficient component Provider solutions

### **Current Situation**

Orders for Al-related power components continue to pour in, with profits recorded for three consecutive months in August, September, and October 2024.

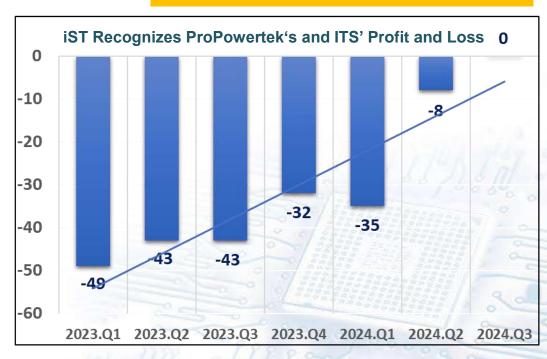
### Outlook for 2025

Wafer Thinning-end: CSP manufacturers continue to invest in AI capital expenditures, and the inventory adjustment in the automotive market is nearing completion.

**Testing-end (Original ITS):** Consumer products (PC/NB) are expected to recover.

**Unit: NTD in millions** 

Losses are Decreasing Quarter By Quarter Q3 2024 Near Break-even Performance









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